

Abstract

[00171] The disclosure provides an alignment device, method and equipment for double-sided exposure, and belongs to the technical field of printed circuit boards. The device comprises positioning signs, marking signs and a position acquisition device. Before each sample to be exposed is exposed, the position information of the positioning signs is acquired by the position acquisition device, so as to obtain the position variation of the positioning signs in actual production. Because the relative positions of the marking signs and the positioning signs are unchanged, the position variation of the marking signs in actual production can be obtained. According to the position variation, the position of an exposure pattern on the other side of the sample to be exposed is adjusted in real time, thereby solving the problem of inaccurate exposure alignment caused by the fact that the marking signs cannot be positioned in real time in the prior art, and improving the accuracy of double-sided alignment of the sample to be exposed.

Fig. 1